

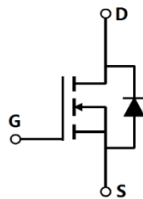
The GreenMOS<sup>®</sup> high voltage MOSFET utilizes charge balance technology to achieve outstanding low on-resistance and lower gate charge. It is engineered to minimize conduction loss, provide superior switching performance and robust avalanche capability.

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Parameter	Value	Unit
$V_{DS, min} @ T_{j(max)}$	650	V
$I_D, pulse$	108	A
$R_{DS(ON), max} @ V_{GS}=10V$	99	
$Q_g$	57.8	nC

Product Name	Package	Marking
OSG60R099FEZF	TO220F	OSG60R099FEZ



**Absolute Maximum Ratings** at  $T_j=25$  unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-source voltage	$V_{DS}$	600	V
Gate-source voltage	$V_{GS}$	$\pm 30$	V
Continuous drain current <sup>1)</sup> , $T_C=25$ °C	$I_D$	36	A
Continuous drain current <sup>1)</sup> , $T_C=100$ °C		22.8	
Pulsed drain current <sup>2)</sup> , $T_C=25$ °C	$I_{D, pulse}$	108	A
Continuous diode forward current <sup>1)</sup> , $T_C=25$ °C	$I_S$	36	A
Diode pulsed current <sup>2)</sup> , $T_C=25$ °C	$I_{S, pulse}$	108	A
Power dissipation <sup>3)</sup> , $T_C=25$ °C	$P_D$	261	W
Single pulsed avalanche energy <sup>5)</sup>	$E_{AS}$	845	mJ
MOSFET dv/dt ruggedness, $V_{DS}$	dv/dt	50	V/ns
Reverse diode dv/dt, $V_{DS}$	dv/dt	50	V/ns
Operation and storage temperature	$T_{stg}, T_j$	-55 to 150	°C

**Thermal Characteristics**

Parameter	Symbol	Value	Unit
Thermal resistance, junction-case	R	3.57	°C/W
Thermal resistance, junction-ambient <sup>4)</sup>	R	62.5	°C/W

**Electrical Characteristics** at  $T_j=25$  unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Drain-source breakdown voltage	$BV_{DSS}$	600			V	$V_{GS}=0$ V, $I_D=1$ mA
		650				$V_{GS}=0$ V, $I_D=1$ mA, $T_j=150$ °C
Gate threshold voltage	$V_{GS(th)}$	3.0		4.5	V	$V_{DS}=V_{GS}$ , $I_D=1$ mA
Drain-source on-state resistance	$R_{DS(ON)}$		0.085	0.099		$V_{GS}=10$ V, $I_D=18$ A
			0.195			$V_{GS}=10$ V, $I_D=18$ A, $T_j=150$ °C
Gate-source leakage current	$I_{GSS}$			100	nA	$V_{GS}=30$ V
				-100		$V_{GS}=-30$ V
Drain-source leakage current	$I_{DSS}$			10	A	$V_{DS}=600$ V, $V_{GS}=0$ V
Gate resistance	$R_G$		6.2			Open drain

### Dynamic Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Input capacitance	$C_{iss}$		3231		pF	$V_{GS}=0\text{ V}$ , $V_{DS}=50\text{ V}$ , Hz
Output capacitance	$C_{oss}$		223.8		pF	
Reverse transfer capacitance	$C_{rss}$		2.2		pF	
Turn-on delay time	$t_{d(on)}$		40.2		ns	$V_{GS}=10\text{ V}$ , $V_{DS}=400\text{ V}$ , $R_G=2.5$ $I_D=16\text{ A}$
Rise time	$t_r$		29.4		ns	
Turn-off delay time	$t_{d(off)}$		87.2		ns	
Fall time	$t_f$		8.4		ns	

### Gate Charge Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Total gate charge	$Q_g$		57.8		nC	$V_{GS}=10\text{ V}$ , $V_{DS}=400\text{ V}$ , $I_D=16\text{ A}$
Gate-source charge	$Q_{gs}$		17.2		nC	
Gate-drain charge	$Q_{gd}$		18.8		nC	
Gate plateau voltage	$V_{plateau}$		5.9		V	

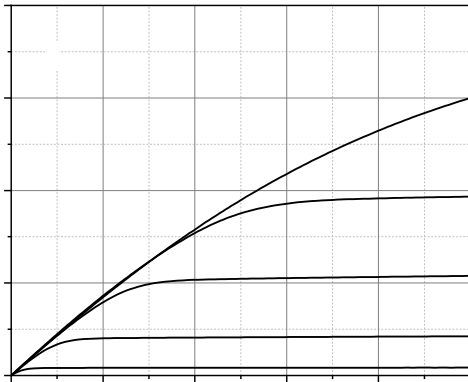
### Body Diode Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Diode forward voltage	$V_{SD}$			1.4	V	$I_S=36\text{ A}$ , $V_{GS}=0\text{ V}$
Reverse recovery time	$t_{rr}$		138		ns	$I_S=16\text{ A}$ ,
Reverse recovery charge	$Q_{rr}$		756		nC	
Peak reverse recovery current	$I_{rrm}$		10.1		A	

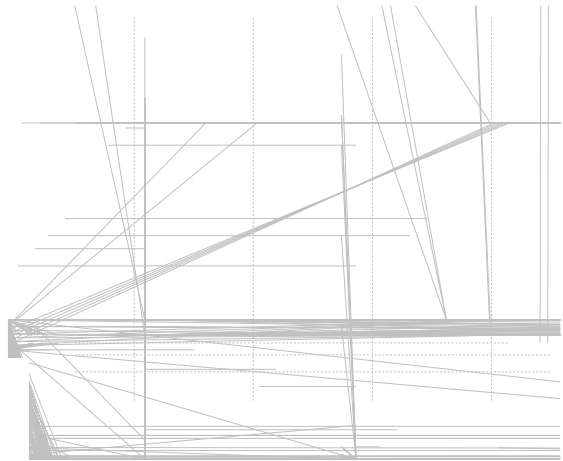
### Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3)  $P_d$  is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of  $R_{\theta}$  is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with  $T_a=25\text{ °C}$ .
- 5)  $V_{DD}=100\text{ V}$ ,  $V_{GS}=10\text{ V}$ ,  $L=80\text{ mH}$ , starting  $T_j=25\text{ °C}$ .

### Electrical Characteristics Diagrams



**Figure 1. Typ. output characteristics**



**Figure 2. Typ. transfer characteristics**

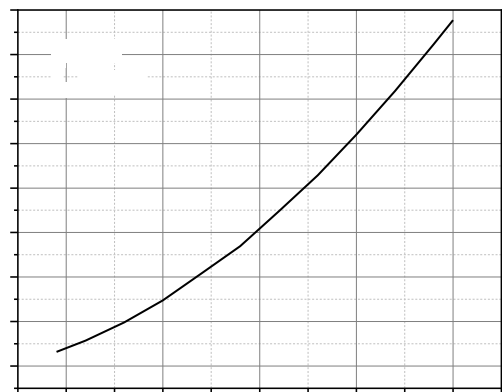


**Figure 3. Typ. capacitances**

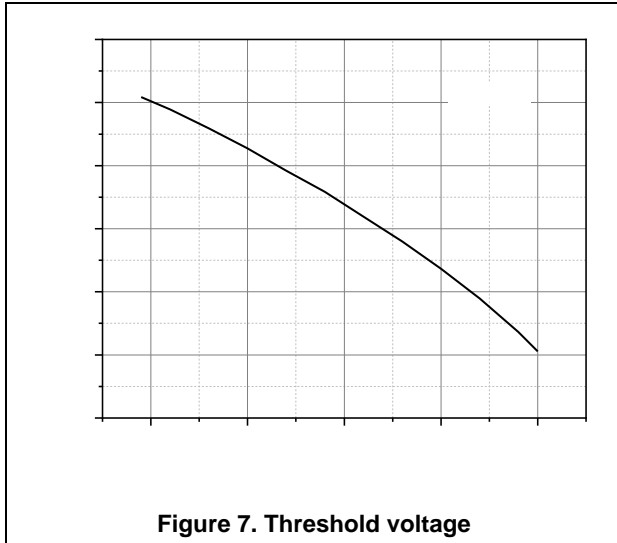


**Figure 4. Typ. gate charge**

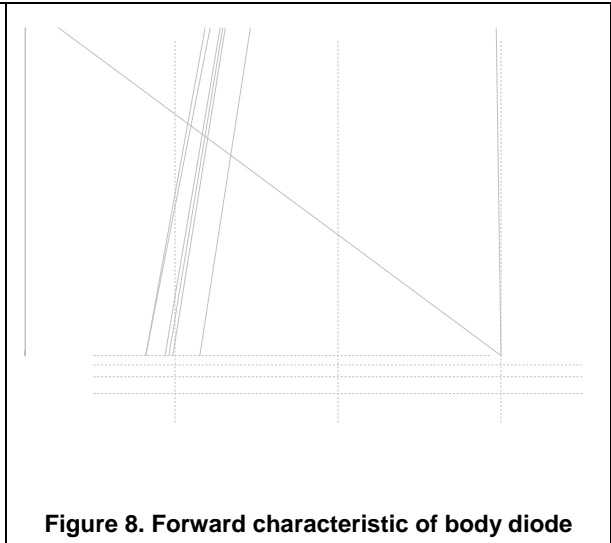
**Figure 5. Drain-source breakdown voltage**



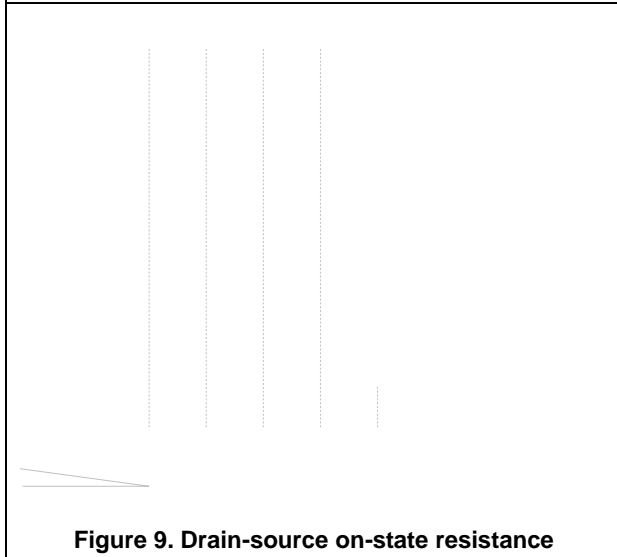
**Figure 6. Drain-source on-state resistance**



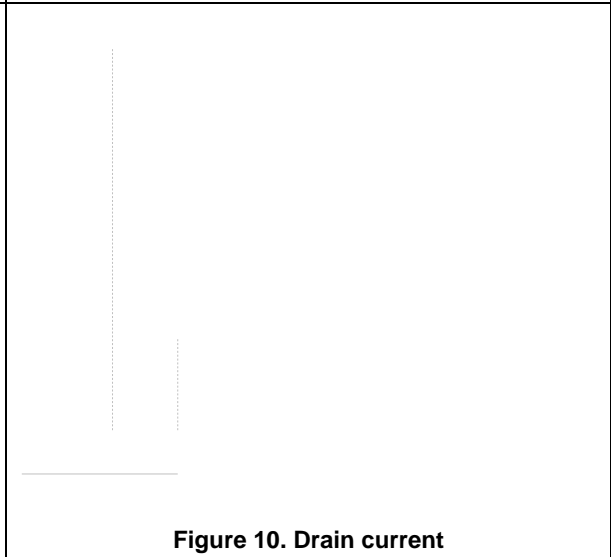
**Figure 7. Threshold voltage**



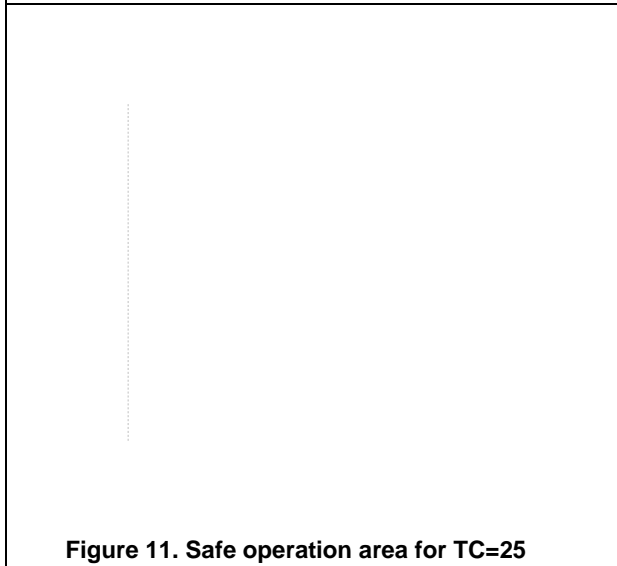
**Figure 8. Forward characteristic of body diode**



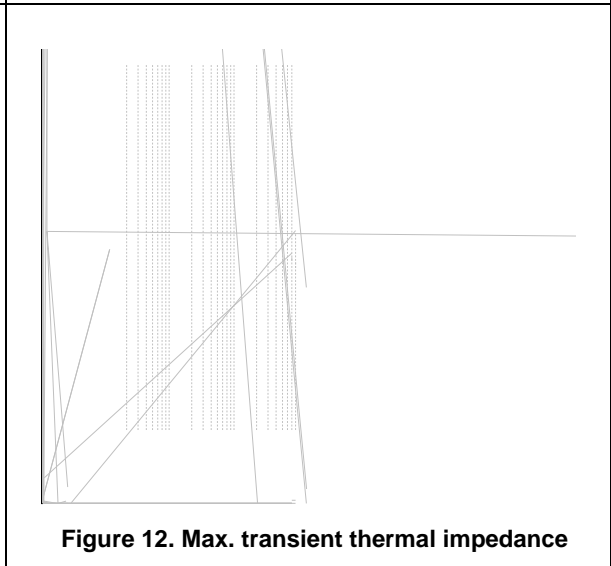
**Figure 9. Drain-source on-state resistance**



**Figure 10. Drain current**

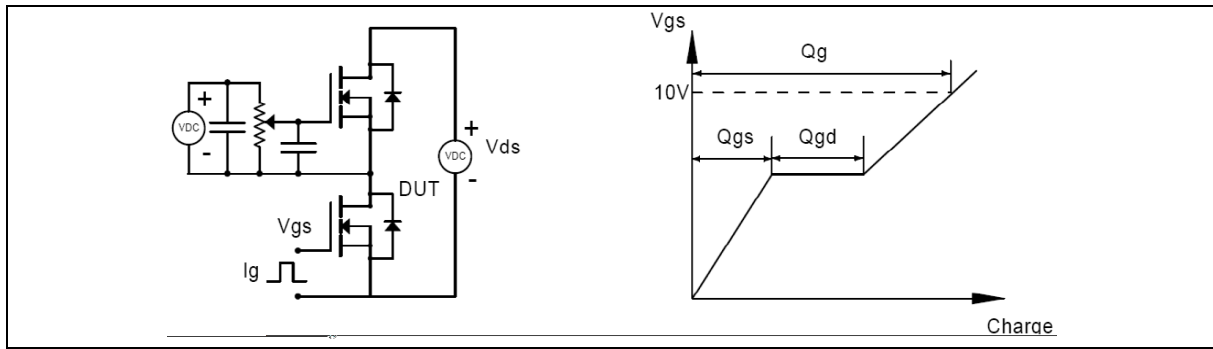


**Figure 11. Safe operation area for TC=25**

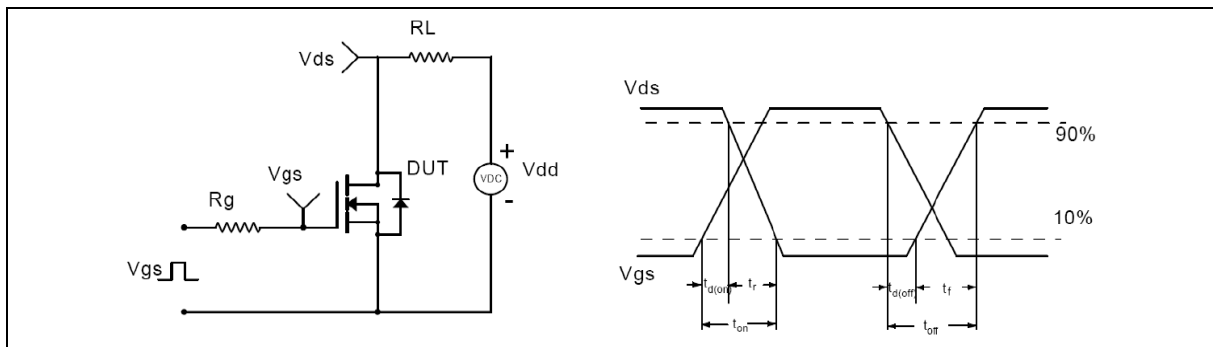


**Figure 12. Max. transient thermal impedance**

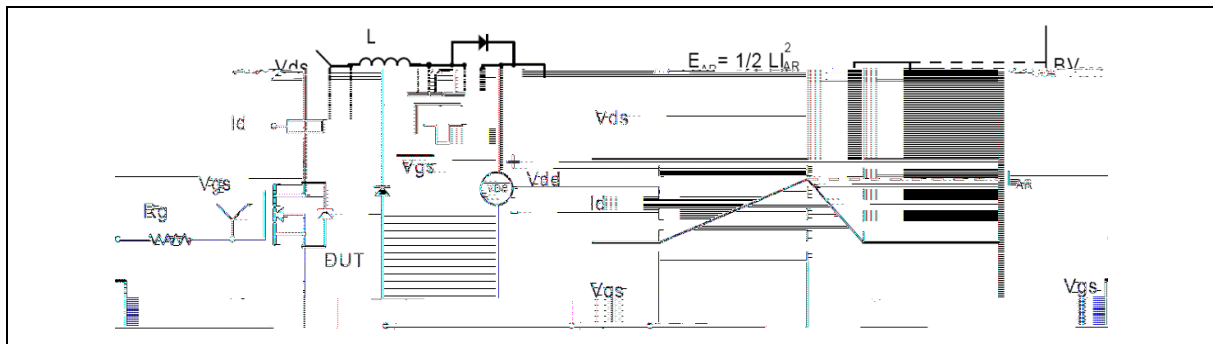
**Test circuits and waveforms**



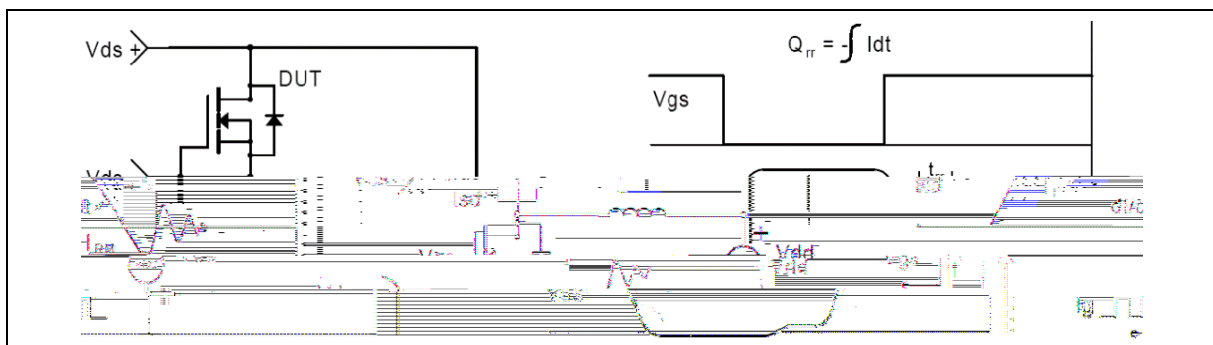
**Figure 1. Gate charge test circuit & waveform**



**Figure 2. Switching time test circuit & waveforms**



**Figure 3. Unclamped inductive switching (UIS) test circuit & waveforms**



**Figure 4. Diode reverse recovery test circuit & waveforms**

**OSG60R099FEZF**

Enhancement Mode N-Channel Power MOSFET

**Ordering Information**

Package Type	Units/ Tube	Tubes / Inner Box	Units/ Inner Box	Inner Boxes/ Carton Box	Units/ Carton Box
TO220F-C	50	20	1000	6	6000

**Product Information**

Product	Package	Pb Free	RoHS	Halogen Free
OSG60R099FEZF	TO220F	yes	yes	yes

